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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Obsolete
Core Processor	RL78
Core Size	16-Bit
Speed	24MHz
Connectivity	CSI, I <sup>2</sup> C, UART/USART
Peripherals	LVD, POR, PWM, WDT
Number of I/O	18
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 11x8/10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	24-WFQFN Exposed Pad
Supplier Device Package	24-HWQFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f10377ana-w5

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Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

RL78/G12 1. OUTLINE

## 1.5 Pin Identification

ANI0 to ANI3,		REGC:	Regulator Capacitance
ANI16 to ANI22:	Analog input	RESET:	Reset
AVREFM:	Analog Reference Voltage Minus	RxD0 to RxD2:	Receive Data
AVREFP:	Analog reference voltage plus	SCK00, SCK01, SCK11,	
EXCLK:	External Clock Input	SCK20:	Serial Clock Input/Output
	(Main System Clock)	SCL00, SCL01,	
INTP0 to INTP5	Interrupt Request From Peripheral	SCL11, SCL20, SCLA0:	Serial Clock Input/Output
KR0 to KR9:	Key Return	SDA00, SDA01, SDA11,	
P00 to P03:	Port 0	SDA20, SDAA0:	Serial Data Input/Output
P10 to P17:	Port 1	SI00, SI01, SI11, SI20:	Serial Data Input
P20 to P23:	Port 2	SO00, SO01, SO11,	
P30 to P31:	Port 3	SO20:	Serial Data Output
P40 to P42:	Port 4	TI00 to TI07:	Timer Input
P50, P51:	Port 5	TO00 to TO07:	Timer Output
P60, P61:	Port 6	TOOL0:	Data Input/Output for Tool
P120 to P122, P125:	Port 12	TOOLRxD, TOOLTxD:	Data Input/Output for External
P137:	Port 13		Device
P147:	Port 14	TxD0 to TxD2:	Transmit Data
PCLBUZ0, PCLBUZ1:	Programmable Clock Output/	VDD:	Power supply
	Buzzer Output	Vss:	Ground
		X1, X2:	Crystal Oscillator (Main System Clock)

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- <R> 2. ELECTRICAL SPECIFICATIONS ( $T_A = -40 \text{ to } +85^{\circ}\text{C}$ )
- <R> This chapter describes the following electrical specifications.
  - Target products A: Consumer applications  $T_A = -40 \text{ to } +85^{\circ}\text{C}$ R5F102xxAxx, R5F103xxAxx
    - D: Industrial applications T<sub>A</sub> = -40 to +85°C R5F102xxDxx, R5F103xxDxx
    - G: Industrial applications when  $T_A = -40$  to  $+105^{\circ}$ C products is used in the range of  $T_A = -40$  to  $+85^{\circ}$ C R5F102xxGxx
  - Cautions 1. The RL78 microcontrollers have an on-chip debug function, which is provided for development and evaluation. Do not use the on-chip debug function in products designated for mass production, because the guaranteed number of rewritable times of the flash memory may be exceeded when this function is used, and product reliability therefore cannot be guaranteed. Renesas Electronics is not liable for problems occurring when the on-chip debug function is used.
    - 2. The pins mounted depend on the product. Refer to 2.1 Port Functions to 2.2.1 Functions for each product.

 $(TA = -40 \text{ to } +85^{\circ}C, 1.8 \text{ V} \le VDD \le 5.5 \text{ V}, Vss = 0 \text{ V})$ 

(3/4)

•		, ,					
Parameter	Symbol	Condition	s	MIN.	TYP.	MAX.	Unit
Input voltage, high	V <sub>IH1</sub>	Normal input buffer		0.8V <sub>DD</sub>		V <sub>DD</sub>	٧
		20-, 24-pin products: P00 to P0 P40 to P42					
		30-pin products: P00, P01, P1 P40, P50, P51, P120, P147					
	V <sub>IH2</sub>	TTL input buffer	$4.0~V \leq V_{DD} \leq 5.5~V$	2.2		V <sub>DD</sub>	٧
		20-, 24-pin products: P10, P11	$3.3~V \leq V_{DD} < 4.0~V$	2.0		V <sub>DD</sub>	٧
		30-pin products: P01, P10, P11, P13 to P17	1.8 V ≤ V <sub>DD</sub> < 3.3 V	1.5		V <sub>DD</sub>	<b>V</b>
	VIH3	P20 to P23	0.7V <sub>DD</sub>		V <sub>DD</sub>	٧	
	V <sub>IH4</sub>	P60, P61	0.7V <sub>DD</sub>		6.0	٧	
_	V <sub>IH5</sub>	P121, P122, P125 <sup>Note 1</sup> , P137, I	0.8V <sub>DD</sub>		V <sub>DD</sub>	٧	
Input voltage, low	VIL1	Normal input buffer	0		0.2V <sub>DD</sub>	٧	
		20-, 24-pin products: P00 to P0 P40 to P42					
		30-pin products: P00, P01, P10 P40, P50, P51, P120, P147	80-pin products: P00, P01, P10 to P17, P30, P31, P40, P50, P51, P120, P147				
	V <sub>IL2</sub>	TTL input buffer	$4.0~V \leq V_{DD} \leq 5.5~V$	0		0.8	>
		20-, 24-pin products: P10, P11	$3.3~V \leq V_{DD} < 4.0~V$	0		0.5	٧
		30-pin products: P01, P10, P11, P13 to P17	$1.8~V \le V_{DD} < 3.3~V$	0		0.32	V
	V <sub>IL3</sub>	P20 to P23		0		0.3V <sub>DD</sub>	٧
	V <sub>IL4</sub>	P60, P61		0		0.3V <sub>DD</sub>	٧
	V <sub>IL5</sub>	P121, P122, P125 <sup>Note 1</sup> , P137, I	EXCLK, RESET	0		0.2V <sub>DD</sub>	٧
Output voltage, high	V <sub>OH1</sub>	20-, 24-pin products: P00 to P03 <sup>Note 2</sup> , P10 to P14,	$4.0 \text{ V} \le \text{V}_{DD} \le 5.5 \text{ V},$ $I_{OH1} = -10.0 \text{ mA}$	V <sub>DD</sub> -1.5			V
		P40 to P42 30-pin products:	$4.0 \text{ V} \le \text{V}_{DD} \le 5.5 \text{ V},$ $I_{OH1} = -3.0 \text{ mA}$	V <sub>DD</sub> -0.7			V
		P00, P01, P10 to P17, P30, P31, P40, P50, P51, P120,	$2.7~V \leq V_{DD} \leq 5.5~V,$ $I_{OH1} = -2.0~mA$	V <sub>DD</sub> -0.6			V
		P147	$1.8 \text{ V} \le \text{V}_{DD} \le 5.5 \text{ V},$ $I_{OH1} = -1.5 \text{ mA}$	V <sub>DD</sub> -0.5			V
	V <sub>OH2</sub>	P20 to P23	Іон2 = -100 μΑ	V <sub>DD</sub> -0.5			V

Notes 1. 20, 24-pin products only.

2. 24-pin products only.

Caution The maximum value of V<sub>IH</sub> of pins P10 to P12 and P41 for 20-pin products, P01, P10 to P12, and P41 for 24-pin products, and P00, P10 to P15, P17, and P50 for 30-pin products is V<sub>DD</sub> even in N-ch open-drain mode. High level is not output in the N-ch open-drain mode.

**Remark** Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.



#### (1) 20-, 24-pin products

 $(T_A = -40 \text{ to } +85^{\circ}\text{C}, 1.8 \text{ V} \le V_{DD} \le 5.5 \text{ V}, \text{Vss} = 0 \text{ V})$ 

(2/2)

Parameter	Symbol			Conditions		MIN.	TYP.	MAX.	Unit
Supply	IDD2 Note 2	HALT	HS (High-speed	fin = 24 MHz <sup>Note 4</sup>	V <sub>DD</sub> = 5.0 V		440	1210	μА
current Note 1		mode	main) mode <sup>Note 6</sup>		V <sub>DD</sub> = 3.0 V		440	1210	1210
			LS (Low-speed	fin = 16 MHz <sup>Note 4</sup>	V <sub>DD</sub> = 5.0 V		400	950	μА
					V <sub>DD</sub> = 3.0 V		400	950	
				fih = 8 MHz <sup>Note 4</sup>	V <sub>DD</sub> = 3.0 V		270	542	μА
		main) mode <sup>Note 6</sup>		V <sub>DD</sub> = 2.0 V		270	542		
			HS (High-speed main) mode Note 6	f <sub>MX</sub> = 20 MHz <sup>Note 3</sup> ,	Square wave input		280	1000	μА
				V <sub>DD</sub> = 5.0 V	Resonator connection		450	1170	
		LS (Low-s		$f_{MX} = 20 \text{ MHz}^{\text{Note 3}},$	Square wave input		280	1000	μА
				V <sub>DD</sub> = 3.0 V	Resonator connection		450	1170	
				$f_{MX} = 10 \text{ MHz}^{\text{Note 3}},$ $V_{DD} = 5.0 \text{ V}$ $f_{MX} = 10 \text{ MHz}^{\text{Note 3}},$ $V_{DD} = 3.0 \text{ V}$	Square wave input		190	590	$\mu$ A
					Resonator connection		260	660	
					Square wave input		190	590	$\mu$ A
					Resonator connection		260	660	
			LS (Low-speed	$f_{MX} = 8 MHz^{Note 3},$	Square wave input		110	360	$\mu$ A
			main) mode Note 6	V <sub>DD</sub> = 3.0 V	Resonator connection		150	416	
				$f_{MX} = 8 MHz^{Note 3},$	Square wave input		110	360	$\mu$ A
				V <sub>DD</sub> = 2.0 V	Resonator connection		150	416	
	IDD3 Note 5	STOP	T <sub>A</sub> = -40°C				0.19	0.50	μА
		mode	T <sub>A</sub> = +25°C				0.24	0.50	
			T <sub>A</sub> = +50°C				0.32	0.80	
			T <sub>A</sub> = +70°C	T <sub>A</sub> = +70°C			0.48	1.20	
			T <sub>A</sub> = +85°C				0.74	2.20	

- Notes 1. Total current flowing into VDD, including the input leakage current flowing when the level of the input pin is fixed to VDD or Vss. The values below the MAX. column include the peripheral operation current. However, not including the current flowing into the A/D converter, LVD circuit, I/O port, and on-chip pull-up/pull-down resistors and the current flowing during data flash rewrite.
  - 2. During HALT instruction execution by flash memory.
  - 3. When high-speed on-chip oscillator clock is stopped.
  - 4. When high-speed system clock is stopped.
  - 5. Not including the current flowing into the 12-bit interval timer and watchdog timer.
  - **6.** Relationship between operation voltage width, operation frequency of CPU and operation mode is as follows.

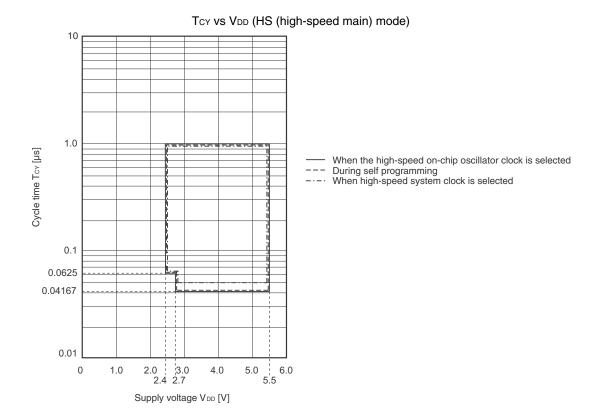
HS(High speed main) mode: VDD = 2.7 V to 5.5 V @1 MHz to 24 MHz

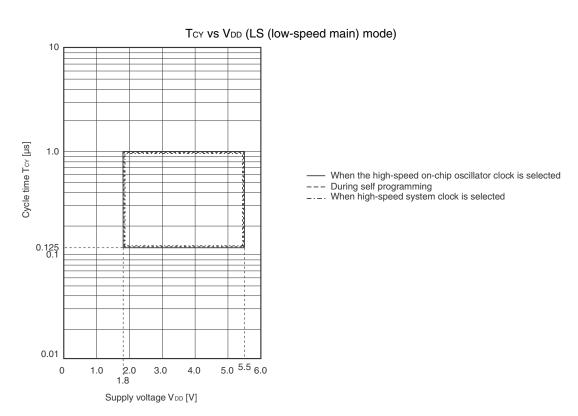
 $V_{\text{DD}}$  = 2.4 V to 5.5 V @1 MHz to 16 MHz

LS(Low speed main) mode: VDD = 1.8 V to 5.5 V @1 MHz to 8 MHz

- Remarks 1. fmx: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)
  - 2. fin: high-speed on-chip oscillator clock frequency
  - 3. Except temperature condition of the TYP. value is  $T_A = 25$ °C, other than STOP mode

### Minimum Instruction Execution Time during Main System Clock Operation





## (2) During communication at same potential (CSI mode) (master mode, SCK00... internal clock output, corresponding CSI00 only)

 $(T_A = -40 \text{ to } +85^{\circ}\text{C}, 2.7 \text{ V} \le V_{DD} \le 5.5 \text{ V}, \text{Vss} = 0 \text{ V})$ 

Parameter	Symbol	Conditions	HS (high-spo	,	LS (low-sp	Unit	
			MIN.	MAX.	MIN.	MAX.	
SCK00 cycle time	tkCY1	tkcy1 ≥ 2/fclk	83.3		250		ns
SCK00 high-/low- tkh1, level width tkl1	$4.0~V \leq V_{DD} \leq 5.5~V$	tkcy1/2-7		tkcy1/2-50		ns	
	t <sub>KL1</sub>	$2.7~V \leq V_{DD} \leq 5.5~V$	tkcy1/2-10		tkcy1/2-50		ns
SI00 setup time	tsıĸı	$4.0~V \leq V_{DD} \leq 5.5~V$	23		110		ns
(to SCK00↑) Note 1		$2.7~V \leq V_{DD} \leq 5.5~V$	33		110		ns
SI00 hold time (from SCK00↑) Note2	tksi1		10		10		ns
Delay time from SCK00↓ to SO00 output Note 3	tkso1	C = 20 pF Note 4		10		10	ns

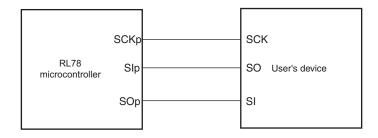
- **Notes 1.** When DAP00 = 0 and CKP00 = 0, or DAP00 = 1 and CKP00 = 1. The SI00 setup time becomes "to  $SCK00\downarrow$ " when DAP00 = 0 and CKP00 = 1, or DAP00 = 1 and CKP00 = 0.
  - 2. When DAP00 = 0 and CKP00 = 0, or DAP00 = 1 and CKP00 = 1. The SI00 hold time becomes "from SCK00 $\downarrow$ " when DAP00 = 0 and CKP00 = 1, or DAP00 = 1 and CKP00 = 0.
  - 3. When DAP00 = 0 and CKP00 = 0, or DAP00 = 1 and CKP00 = 1. The delay time to SO00 output becomes "from SCK00 $\uparrow$ " when DAP00 = 0 and CKP00 = 1, or DAP00 = 1 and CKP00 = 0.
  - 4. C is the load capacitance of the SCK00 and SO00 output lines.

**Caution** Select the normal input buffer for the SI00 pin and the normal output mode for the SO00 and SCK00 pins by using port input mode register 1 (PIM1) and port output mode register 1 (POM1).

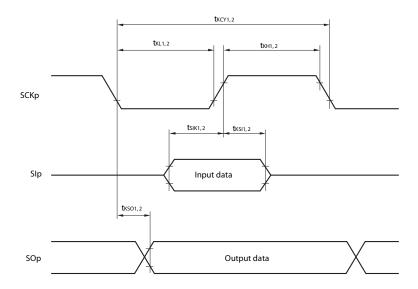
Remarks 1. This specification is valid only when CSI00's peripheral I/O redirect function is not used.

 fmck: Serial array unit operation clock frequency (Operation clock to be set by the serial clock select register 0 (SPS0) and the CKS00 bit of serial mode register 00 (SMR00).)

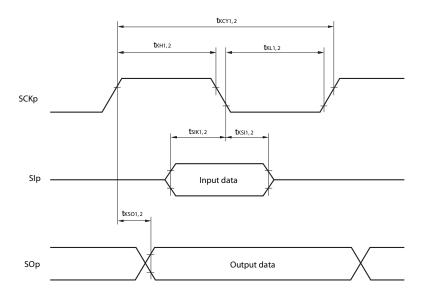
### CSI mode connection diagram (during communication at same potential)



## CSI mode serial transfer timing (during communication at same potential) (When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.)



# CSI mode serial transfer timing (during communication at same potential) (When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.)



(Remarks are listed on the next page.)

#### 2.5.2 Serial interface IICA

 $(T_A = -40 \text{ to } +85^{\circ}\text{C}, 1.8 \text{ V} \le V_{DD} \le 5.5 \text{ V}, \text{Vss} = 0 \text{ V})$ 

Parameter	Symbol	Conditions	HS	HS (high-speed main) mode			Unit
			LS	LS (low-speed main) mode			
			Standa	rd Mode	Fast Mode		
			MIN.	MAX.	MIN.	MAX.	
SCLA0 clock frequency	fscL	Fast mode: fclk≥ 3.5 MHz			0	400	kHz
		Normal mode: fclk≥ 1 MHz	0	100			kHz
Setup time of restart condition	tsu:sta		4.7		0.6		μS
Hold time <sup>Note 1</sup>	thd:sta		4.0		0.6		μS
Hold time when SCLA0 = "L"	tLOW		4.7		1.3		μS
Hold time when SCLA0 = "H"	tніgн		4.0		0.6		μS
Data setup time (reception)	tsu:dat		250		100		ns
Data hold time (transmission) <sup>Note 2</sup>	thd:dat		0	3.45	0	0.9	μS
Setup time of stop condition	tsu:sto		4.0		0.6		μS
Bus-free time	tBUF		4.7		1.3		μS

Notes 1. The first clock pulse is generated after this period when the start/restart condition is detected.

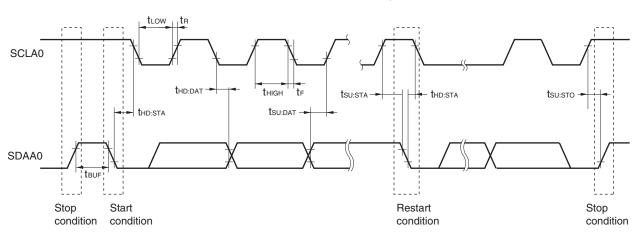
2. The maximum value (MAX.) of thd:DAT is during normal transfer and a wait state is inserted in the ACK (acknowledge) timing.

Caution Only in the 30-pin products, the values in the above table are applied even when bit 2 (PIOR2) in the peripheral I/O redirection register (PIOR) is 1. At this time, the pin characteristics (IoH1, IoL1, VoH1, VoL1) must satisfy the values in the redirect destination.

**Remark** The maximum value of Cb (communication line capacitance) and the value of Rb (communication line pull-up resistor) at that time in each mode are as follows.

Normal mode:  $C_b$  = 400 pF, Rb = 2.7 k $\Omega$ Fast mode:  $C_b$  = 320 pF, Rb = 1.1 k $\Omega$ 

### IICA serial transfer timing



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(3) When reference voltage (+) = V<sub>DD</sub> (ADREFP1 = 0, ADREFP0 = 0), reference voltage (-) = V<sub>SS</sub> (ADREFM = 0), target pin: ANI0 to ANI3, ANI16 to ANI22, internal reference voltage, and temperature sensor output voltage

 $(T_A = -40 \text{ to } +85^{\circ}\text{C}, 1.8 \text{ V} \le V_{DD} \le 5.5 \text{ V}, V_{SS} = 0 \text{ V}, \text{ Reference voltage (+)} = V_{DD}, \text{ Reference voltage (-)} = V_{SS})$ 

Parameter	Symbol	Condition	ns	MIN.	TYP.	MAX.	Unit
Resolution	Res			8		10	bit
Overall error <sup>Note 1</sup>	AINL	10-bit resolution			1.2	±7.0	LSB
					1.2	$\pm 10.5$ Note 3	LSB
Conversion time	tconv	10-bit resolution	$3.6~V \leq V_{DD} \leq 5.5~V$	2.125		39	μs
		Target pin: ANI0 to ANI3, ANI16 to ANI22	$2.7~V \leq V_{DD} \leq 5.5~V$	3.1875		39	μS
		ANTIO IO ANIZZ	$1.8~V \leq V_{DD} \leq 5.5~V$	17		39	μs
				57		95	μS
Conversion time	tconv	10-bit resolution	$3.6~V \leq V_{DD} \leq 5.5~V$	2.375		39	μS
		voltage, and temperature	$2.7 \text{ V} \leq \text{VDD} \leq 5.5 \text{ V}$	3.5625		39	μS
	sensor		$2.4~V \leq V_{DD} \leq 5.5~V$	17		39	μS
Zero-scale error <sup>Notes 1, 2</sup>	EZS	10-bit resolution				±0.60	%FSR
						±0.85	%FSR
Full-scale errorNotes 1, 2	EFS	10-bit resolution			±0.60	%FSR	
						±0.85	%FSR
Integral linearity error <sup>Note 1</sup>	ILE	10-bit resolution				±4.0	LSB
						±6.5 Note 3	LSB
Differential linearity error Note 1	DLE	10-bit resolution				±2.0	LSB
						±2.5 Note 3	LSB
Analog input voltage	VAIN	ANI0 to ANI3, ANI16 to ANI2	2	0		V <sub>DD</sub>	V
		Internal reference voltage (2.4 V $\leq$ VDD $\leq$ 5.5 V, HS (high	VBGR Note 4			V	
		Temperature sensor output v (2.4 V $\leq$ VDD $\leq$ 5.5 V, HS (high	•	VTMPS25 Note 4		1	V

Notes 1. Excludes quantization error (±1/2 LSB).

- 2. This value is indicated as a ratio (%FSR) to the full-scale value.
- **3.** When the conversion time is set to 57  $\mu$ s (min.) and 95  $\mu$ s (max.).
- 4. Refer to 28.6.2 Temperature sensor/internal reference voltage characteristics.

(4) When reference voltage (+) = Internal reference voltage (ADREFP1 = 1, ADREFP0 = 0), reference voltage (-) = AVREFM (ADREFM = 1), target pin: ANI0, ANI2, ANI3, and ANI16 to ANI22

(Ta = -40 to +85°C, 2.4 V  $\leq$  VDD  $\leq$  5.5 V, Vss = 0 V, Reference voltage (+) = VBGR Note 3, Reference voltage (-) = AVREFM Note 4 = 0 V, HS (high-speed main) mode)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Resolution	Res			8		bit
Conversion time	tconv	8-bit resolution	17		39	μs
Zero-scale error <sup>Notes 1, 2</sup>	EZS	8-bit resolution			±0.60	%FSR
Integral linearity error <sup>Note 1</sup>	ILE	8-bit resolution			±2.0	LSB
Differential linearity error Note 1	DLE	8-bit resolution			±1.0	LSB
Analog input voltage	VAIN		0		VBGR Note 3	V

- **Notes 1.** Excludes quantization error ( $\pm 1/2$  LSB).
  - 2. This value is indicated as a ratio (%FSR) to the full-scale value.
  - 3. Refer to 28.6.2 Temperature sensor/internal reference voltage characteristics.
  - **4.** When reference voltage (–) = Vss, the MAX. values are as follows.

Zero-scale error: Add ±0.35%FSR to the MAX. value when reference voltage (-) = AVREFM.

Integral linearity error: Add  $\pm 0.5$  LSB to the MAX. value when reference voltage (–) = AVREFM.

Differential linearity error: Add ±0.2 LSB to the MAX. value when reference voltage (-) = AVREFM.

### LVD detection voltage of interrupt & reset mode

(T<sub>A</sub> = -40 to +85°C, V<sub>PDR</sub>  $\leq$  V<sub>DD</sub>  $\leq$  5.5 V, V<sub>SS</sub> = 0 V)

Parameter	Symbol		Con	MIN.	TYP.	MAX.	Unit	
Interrupt and reset	V <sub>LVDB0</sub>	V <sub>POC2</sub> ,	VPOC1, VPOC0 = 0, 0, 1, fa	1.80	1.84	1.87	V	
mode	V <sub>LVDB1</sub>		LVIS1, LVIS0 = 1, 0	Rising reset release voltage	1.94	1.98	2.02	V
				Falling interrupt voltage	1.90	1.94	1.98	V
	V <sub>LVDB2</sub>		LVIS1, LVIS0 = 0, 1	Rising reset release voltage	2.05	2.09	2.13	V
				Falling interrupt voltage	2.00	2.04	2.08	V
	V <sub>LVDB3</sub>		LVIS1, LVIS0 = 0, 0	Rising reset release voltage	3.07	3.13	3.19	V
				Falling interrupt voltage	3.00	3.06	3.12	V
	V <sub>LVDC0</sub>	V <sub>POC2</sub> ,	/POC1, VPOC0 = 0, 1, 0, falling reset voltage		2.40	2.45	2.50	V
	V <sub>LVDC1</sub>		LVIS1, LVIS0 = 1, 0	Rising reset release voltage	2.56	2.61	2.66	V
				Falling interrupt voltage	2.50	2.55	2.60	V
	V <sub>LVDC2</sub>		LVIS1, LVIS0 = 0, 1	Rising reset release voltage	2.66	2.71	2.76	V
				Falling interrupt voltage	2.60	2.65	2.70	V
	V <sub>LVDC3</sub>		LVIS1, LVIS0 = 0, 0	Rising reset release voltage	3.68	3.75	3.82	V
				Falling interrupt voltage	3.60	3.67	3.74	V
	V <sub>LVDD0</sub>	V <sub>POC2</sub> ,	VPOC1, VPOC1 = 0, 1, 1, fa	lling reset voltage	2.70	2.75	2.81	V
	V <sub>LVDD1</sub>		LVIS1, LVIS0 = 1, 0	Rising reset release voltage	2.86	2.92	2.97	V
				Falling interrupt voltage	2.80	2.86	2.91	V
	V <sub>LVDD2</sub>		LVIS1, LVIS0 = 0, 1	Rising reset release voltage	2.96	3.02	3.08	V
				Falling interrupt voltage	2.90	2.96	3.02	V
	V <sub>LVDD3</sub>		LVIS1, LVIS0 = 0, 0	Rising reset release voltage	3.98	4.06	4.14	V
				Falling interrupt voltage	3.90	3.98	4.06	V

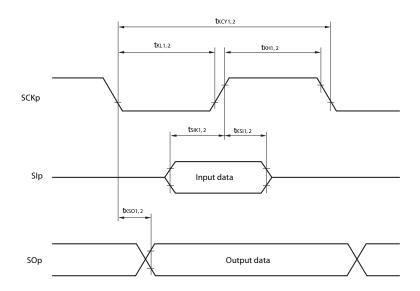
### 2.6.5 Power supply voltage rising slope characteristics

### $(T_A = -40 \text{ to } +85^{\circ}\text{C}, \text{ Vss} = 0 \text{ V})$

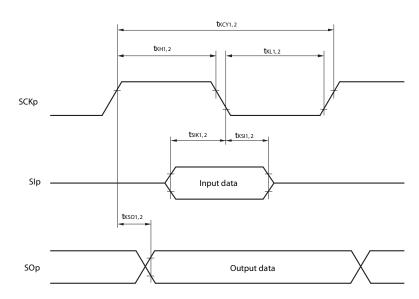
Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Power supply voltage rising slope	SVDD				54	V/ms

**Caution** Make sure to keep the internal reset state by the LVD circuit or an external reset until V<sub>DD</sub> reaches the operating voltage range shown in 28.4 AC Characteristics.

## CSI mode serial transfer timing (during communication at same potential) (When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.)



## CSI mode serial transfer timing (during communication at same potential) (When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.)



**Remarks 1.** p: CSI number (p = 00, 01, 11, 20), m: Unit number (m = 0, 1), n: Channel number (n = 0, 1, 3)

2. fmck: Serial array unit operation clock frequency (Operation clock to be set by the serial clock select register m (SPSm) and the CKSmn bit of serial mode register mn (SMRmn). m: Unit number (m = 0,1), n: Channel number (n = 0, 1, 3))

### (5) Communication at different potential (1.8 V, 2.5 V, 3 V) (UART mode)

 $(T_A = -40 \text{ to } +105^{\circ}\text{C}, 2.4 \text{ V} \le V_{DD} \le 5.5 \text{ V}, \text{Vss} = 0 \text{ V})$ 

Parameter	Symbol		Conditions		speed main) ode	Unit
				MIN.	MAX.	
Transfer rate Note4		Reception	Reception $4.0 \text{ V} \leq \text{V}_{DD} \leq 5.5 \text{ V},$ $2.7 \text{ V} \leq \text{V}_{b} \leq 4.0 \text{ V}$		fMCK/12 Note 1	bps
			Theoretical value of the maximum transfer rate $f_{MCK} = f_{CLK}^{Note 2}$		2.0	Mbps
		$2.7 \text{ V} \le \text{V}_{DD} < 4.0 \text{ V},$ $2.3 \text{ V} \le \text{V}_{b} \le 2.7 \text{ V}$		fMCK/12 Note 1	bps	
	Theoretical value of the maximum transfer rate $f_{MCK} = f_{CLK}^{Note \ 2}$		2.0	Mbps		
	$2.4 \text{ V} \le \text{V}_{DD} < 3.3 \text{ V},$ $1.6 \text{ V} \le \text{V}_{b} \le 2.0 \text{ V}$		fMCK/12 Note 1	bps		
		Theoretical value of the maximum transfer rate $f_{MCK} = f_{CLK}^{Note \ 2}$		2.0	Mbps	
		Transmission	$4.0 \text{ V} \le V_{DD} \le 5.5 \text{ V},$ $2.7 \text{ V} \le V_b \le 4.0 \text{ V}$		Note 3	bps
			Theoretical value of the maximum transfer rate $C_b = 50$ pF, $R_b = 1.4$ k $\Omega$ , $V_b = 2.7$ V		2.0 Note 4	Mbps
			$2.7 \text{ V} \le \text{V}_{DD} < 4.0 \text{ V},$ $2.3 \text{ V} \le \text{V}_{b} \le 2.7 \text{ V},$		Note 5	bps
			Theoretical value of the maximum transfer rate $C_b = 50 \text{ pF},  R_b = 2.7 \text{ k}\Omega,  V_b = 2.3 \text{ V}$		1.2 Note 6	Mbps
			$2.4 \text{ V} \le \text{V}_{DD} < 3.3 \text{ V},$ $1.6 \text{ V} \le \text{V}_{b} \le 2.0 \text{ V}$		Notes 2, 7	bps
			Theoretical value of the maximum transfer rate $C_b = 50 \text{ pF}, R_b = 5.5 \text{ k}\Omega, V_b = 1.6 \text{ V}$		0.43 Note 8	Mbps

Notes 1. Transfer rate in the SNOOZE mode is 4800 bps only.

2. The maximum operating frequencies of the CPU/peripheral hardware clock (fclk) are:

HS (high-speed main) mode: 24 MHz (2.7 V  $\leq$  VDD  $\leq$  5.5 V)

16 MHz (2.4 V 
$$\leq$$
 V<sub>DD</sub>  $\leq$  5.5 V)

3. The smaller maximum transfer rate derived by using fmck/12 or the following expression is the valid maximum transfer rate.

Expression for calculating the transfer rate when 4.0 V  $\leq$  VDD  $\leq$  5.5 V and 2.7 V  $\leq$  Vb  $\leq$  4.0 V

$$\label{eq:maximum transfer rate} \text{Maximum transfer rate} = \frac{1}{\{-C_b \times R_b \times \text{ln } (1-\frac{2.2}{V_b})\} \times 3} \text{ [bps]}$$

## (6) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI mode) (master mode, SCKp... internal clock output) (3/3)

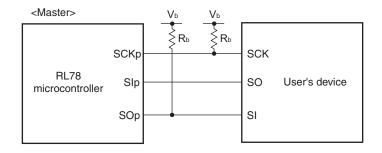
 $(T_A = -40 \text{ to } +105^{\circ}\text{C}, 2.4 \text{ V} \le V_{DD} \le 5.5 \text{ V}, \text{Vss} = 0 \text{ V})$ 

Parameter	Symbol	Conditions	HS (high-speed	I main) Mode	Unit
			MIN.	MAX.	
SIp setup time (to SCKp↓)	tsıkı	$ 4.0~V \leq V_{DD} \leq 5.5~V,~2.7~V \leq V_b \leq 4.0~V, $ $C_b = 30~pF,~R_b = 1.4~k\Omega $	88		ns
		$ \label{eq:continuous}                                   $	88		ns
		$ \label{eq:continuous}                                   $	220		ns
SIp hold time (from SCKp↓) Note	tksii	$ \begin{aligned} 4.0 \ V &\leq V_{DD} \leq 5.5 \ V, \ 2.7 \ V \leq V_b \leq 4.0 \ V, \\ C_b &= 30 \ pF, \ R_b = 1.4 \ k\Omega \end{aligned} $	38		ns
		$ 2.7 \ V \leq V_{DD} < 4.0 \ V, \ 2.3 \ V \leq V_b \leq 2.7 \ V, $ $C_b = 30 \ pF, \ R_b = 2.7 \ k\Omega $	38		ns
		$ \label{eq:continuous}                                   $	38		ns
Delay time from SCKp↑ to SOp output Note	tkso1	$ \begin{aligned} 4.0 \ V &\leq V_{DD} \leq 5.5 \ V, \ 2.7 \ V \leq V_b \leq 4.0 \ V, \\ C_b &= 30 \ pF, \ R_b = 1.4 \ k\Omega \end{aligned} $		50	ns
		$ 2.7 \ V \leq V_{DD} < 4.0 \ V, \ 2.3 \ V \leq V_b \leq 2.7 \ V, $ $C_b = 30 \ pF, \ R_b = 2.7 \ k\Omega $		50	ns
				50	ns

**Note** When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

- Cautions 1. Select the TTL input buffer for the SIp pin and the N-ch open drain output (VDD tolerance) mode for the SOp pin and SCKp pin by using port input mode register 1 (PIM1) and port output mode register 1 (POM1). For VIH and VIL, see the DC characteristics with TTL input buffer selected.
  - 2. CSI01 and CSI11 cannot communicate at different potential.
- **Remarks 1.** Rb  $[\Omega]$ : Communication line (SCKp, SOp) pull-up resistance, Cb [F]: Communication line (SCKp, SOp) load capacitance, Vb [V]: Communication line voltage
  - 2. p: CSI number (p = 00, 20), m: Unit number (m = 0, 1), n: Channel number (n = 0)

### CSI mode connection diagram (during communication at different potential)



#### 3.5.2 Serial interface IICA

 $(T_A = -40 \text{ to } +105^{\circ}\text{C}, 2.4 \text{ V} \le V_{DD} \le 5.5 \text{ V}, \text{Vss} = 0 \text{ V})$ 

Parameter	Symbol	Conditions	HS	HS (high-speed main			Unit
			Standa	rd Mode	Fast	Mode	
			MIN.	MAX.	MIN.	MAX.	
SCLA0 clock frequency	fscL	Fast mode: fclk≥ 3.5 MHz			0	400	kHz
		Normal mode: fclk≥ 1 MHz	0	100			kHz
Setup time of restart condition	tsu:sta		4.7		0.6		μS
Hold time <sup>Note 1</sup>	thd:STA		4.0		0.6		μS
Hold time when SCLA0 = "L"	tLOW		4.7		1.3		μS
Hold time when SCLA0 = "H"	thigh		4.0		0.6		μS
Data setup time (reception)	tsu:dat		250		100		ns
Data hold time (transmission) <sup>Note 2</sup>	thd:dat		0	3.45	0	0.9	μS
Setup time of stop condition	tsu:sto		4.0		0.6		μS
Bus-free time	<b>t</b> BUF		4.7		1.3		μS

Notes 1. The first clock pulse is generated after this period when the start/restart condition is detected.

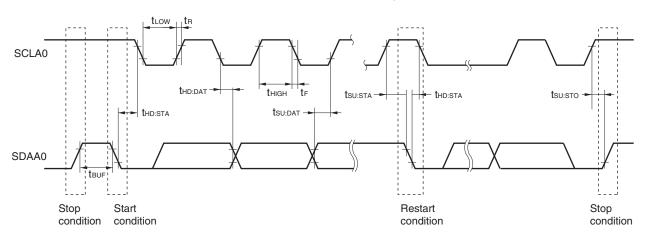
2. The maximum value (MAX.) of thd:DAT is during normal transfer and a wait state is inserted in the ACK (acknowledge) timing.

Caution Only in the 30-pin products, the values in the above table are applied even when bit 2 (PIOR2) in the peripheral I/O redirection register (PIOR) is 1. At this time, the pin characteristics (IoH1, IoL1, VoH1, VoL1) must satisfy the values in the redirect destination.

**Remark** The maximum value of C<sub>b</sub> (communication line capacitance) and the value of R<sub>b</sub> (communication line pull-up resistor) at that time in each mode are as follows.

Normal mode:  $C_b = 400 \text{ pF}, \text{ Rb} = 2.7 \text{ k}\Omega$ Fast mode:  $C_b = 320 \text{ pF}, \text{ Rb} = 1.1 \text{ k}\Omega$ 

#### IICA serial transfer timing



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(3) When reference voltage (+) = V<sub>DD</sub> (ADREFP1 = 0, ADREFP0 = 0), reference voltage (-) = V<sub>SS</sub> (ADREFM = 0), target pin: ANI0 to ANI3, ANI16 to ANI22, internal reference voltage, and temperature sensor output voltage

 $(T_A = -40 \text{ to } +105^{\circ}\text{C}, 2.4 \text{ V} \le V_{DD} \le 5.5 \text{ V}, \text{Vss} = 0 \text{ V}, \text{Reference voltage (+)} = V_{DD}, \text{ Reference voltage (-)} = V_{SS})$ 

Parameter	Symbol	Condition	ns	MIN.	TYP.	MAX.	Unit
Resolution	Res			8		10	bit
Overall error <sup>Note 1</sup>	AINL	10-bit resolution			1.2	±7.0	LSB
Conversion time	tconv	10-bit resolution	$3.6~V \leq V_{DD} \leq 5.5~V$	2.125		39	μs
			$2.7~V \leq V_{DD} \leq 5.5~V$	3.1875		39	μs
		ANI16 to ANI22	$2.4~V \leq V_{DD} \leq 5.5~V$	17		39	μs
Conversion time	tconv	10-bit resolution	$3.6~V \leq V_{DD} \leq 5.5~V$	2.375		39	μs
		Target pin: internal reference	$2.7 \text{ V} \leq \text{VDD} \leq 5.5 \text{ V}$	3.5625		39	μs
		voltage, and temperature sensor output voltage (HS (high-speed main) mode)	$2.4~V \leq V_{DD} \leq 5.5~V$	17		39	μs
Zero-scale error <sup>Notes 1, 2</sup>	EZS	10-bit resolution	, , ,			±0.60	%FSR
Full-scale errorNotes 1, 2	EFS	10-bit resolution	10-bit resolution			±0.60	%FSR
Integral linearity error <sup>Note 1</sup>	ILE	10-bit resolution				±4.0	LSB
Differential linearity error Note 1	DLE	10-bit resolution				±2.0	LSB
Analog input voltage	VAIN	ANI0 to ANI3, ANI16 to ANI2	0		V <sub>DD</sub>	٧	
		Internal reference voltage (HS (high-speed main) mode)			VBGR Note 3		V
		Temperature sensor output v (HS (high-speed main) mode)		VTMPS25 Note 3	1	V	

Notes 1. Excludes quantization error ( $\pm 1/2$  LSB).

- 2. This value is indicated as a ratio (%FSR) to the full-scale value.
- 3. Refer to 29.6.2 Temperature sensor/internal reference voltage characteristics.

### 3.6.2 Temperature sensor/internal reference voltage characteristics

(T<sub>A</sub> = -40 to +105°C, 2.4 V  $\leq$  V<sub>DD</sub>  $\leq$  5.5 V, V<sub>SS</sub> = 0 V, HS (high-speed main) mode

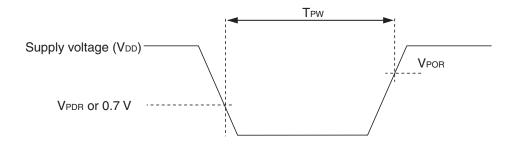
Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Temperature sensor output voltage	V <sub>TMPS25</sub>	Setting ADS register = 80H, TA = +25°C		1.05		V
Internal reference voltage	V <sub>BGR</sub>	Setting ADS register = 81H	1.38	1.45	1.50	V
Temperature coefficient	Fvтмps	Temperature sensor output voltage that depends on the temperature		-3.6		mV/°C
Operation stabilization wait time	tamp		5			μs

### 3.6.3 POR circuit characteristics

 $(T_A = -40 \text{ to } +105^{\circ}\text{C}, \text{ Vss} = 0 \text{ V})$ 

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Detection voltage	VPOR	Power supply rise time	1.45	1.51	1.57	V
	V <sub>PDR</sub>	Power supply fall time	1.44	1.50	1.56	V
Minimum pulse width Note	T <sub>PW</sub>		300			μs

Note Minimum time required for a POR reset when V<sub>DD</sub> exceeds below V<sub>PDR</sub>. This is also the minimum time required for a POR reset from when V<sub>DD</sub> exceeds below 0.7 V to when V<sub>DD</sub> exceeds V<sub>PDR</sub> while STOP mode is entered or the main system clock is stopped through setting bit 0 (HIOSTOP) and bit 7 (MSTOP) in the clock operation status control register (CSC).



### LVD detection voltage of interrupt & reset mode

(TA = -40 to +105°C, VPDR  $\leq$  VDD  $\leq$  5.5 V, Vss = 0 V)

Parameter	Symbol	Conditions			MIN.	TYP.	MAX.	Unit
Interrupt and reset	V <sub>LVDD0</sub>	VPOC2,	VPOC1, VPOC1 = 0, 1, 1, falli	ng reset voltage	2.64	2.75	2.86	V
mode	V <sub>LVDD1</sub>		LVIS1, LVIS0 = 1, 0	Rising reset release voltage	2.81	2.92	3.03	V
				Falling interrupt voltage	2.75	2.86	2.97	V
	V <sub>LVDD2</sub>		LVIS1, LVIS0 = 0, 1	Rising reset release voltage	2.90	3.02	3.14	V
				Falling interrupt voltage	2.85	2.96	3.07	V
	V <sub>LVDD3</sub>		LVIS1, LVIS0 = 0, 0	Rising reset release voltage	3.90	4.06	4.22	V
				Falling interrupt voltage	3.83	3.98	4.13	V

### 3.6.5 Power supply voltage rising slope characteristics

### $(T_A = -40 \text{ to } +105^{\circ}\text{C}, \text{ Vss} = 0 \text{ V})$

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Power supply voltage rising slope	SVDD				54	V/ms

Caution Make sure to keep the internal reset state by the LVD circuit or an external reset until V<sub>DD</sub> reaches the operating voltage range shown in 29.4 AC Characteristics.

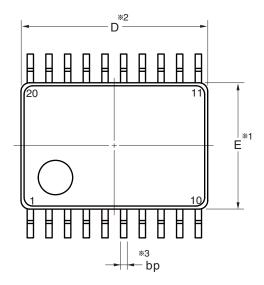
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### 4. PACKAGE DRAWINGS

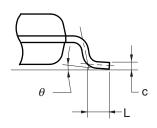
### 4.1 20-pin products

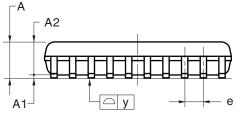
R5F1026AASP, R5F10269ASP, R5F10268ASP, R5F10267ASP, R5F10266ASP R5F1036AASP, R5F10369ASP, R5F10368ASP, R5F10367ASP, R5F10366ASP R5F1026ADSP, R5F10269DSP, R5F10268DSP, R5F10267DSP, R5F10266DSP R5F1036ADSP, R5F10369DSP, R5F10368DSP, R5F10367DSP, R5F10366DSP R5F1026AGSP, R5F10269GSP, R5F10268GSP, R5F10267GSP, R5F10266GSP

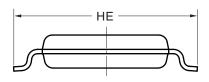
JEITA Package Code	RENESAS Code	Previous Code	MASS (TYP.) [g]
P-LSSOP20-4.4x6.5-0.65	PLSP0020JB-A	P20MA-65-NAA-1	0.1



detail of lead end







#### NOTE

- 1.Dimensions "X1" and "X2" do not include mold flash.
- 2.Dimension "X3" does not include trim offset.

	(UNIT:mm)
ITEM	DIMENSIONS
D	6.50±0.10
E	4.40±0.10
HE	6.40±0.20
Α	1.45 MAX.
A1	0.10±0.10
A2	1.15
е	0.65±0.12
bp	$0.22 + 0.10 \\ -0.05$
С	$0.15 + 0.05 \\ -0.02$
L	0.50±0.20
У	0.10
$\theta$	0° to 10°

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## RL78/G12 Data Sheet

			Description
Rev.	Date	Page	Summary
1.00	Dec 10, 2012	-	First Edition issued
2.00	Sep 06, 2013	1	Modification of 1.1 Features
		3	Modification of 1.2 List of Part Numbers
		4	Modification of Table 1-1. List of Ordering Part Numbers, Note, and Caution
		7 to 9	Modification of package name in 1.4.1 to 1.4.3
		14	Modification of tables in 1.7 Outline of Functions
		17	Modification of description of table in 2.1 Absolute Maximum Ratings (TA = 25°C)
		18	Modification of table, Note, and Caution in 2.2.1 X1 oscillator characteristics
		18	Modification of table in 2.2.2 On-chip oscillator characteristics
		19	Modification of Note 3 in 2.3.1 Pin characteristics (1/4)
		20	Modification of Note 3 in 2.3.1 Pin characteristics (2/4)
		23	Modification of Notes 1 and 2 in (1) 20-, 24-pin products (1/2)
		24	Modification of Notes 1 and 3 in (1) 20-, 24-pin products (2/2)
		25	Modification of Notes 1 and 2 in (2) 30-pin products (1/2)
		26	Modification of Notes 1 and 3 in (2) 30-pin products (2/2)
		27	Modification of (3) Peripheral functions (Common to all products)
		28	Modification of table in 2.4 AC Characteristics
		29	Addition of Minimum Instruction Execution Time during Main System Clock Operation
		30	Modification of figures of AC Timing Test Point and External Main System Clock Timing
		31	Modification of figure of AC Timing Test Point
		31	Modification of description and Note 2 in (1) During communication at same potential
		01	(UART mode)
		32	Modification of description in (2) During communication at same potential (CSI mode)
			Modification of description in (3) During communication at same potential (CSI mode)
		33	
		34	Modification of description in (4) During communication at same potential (CSI mode)
		36	Modification of table and Note 2 in (5) During communication at same potential
			(simplified I <sup>2</sup> C mode)
		38, 39	Modification of table and Notes 1 to 9 in (6) Communication at different potential
			(1.8 V, 2.5 V, 3 V) (UART mode)
		40	Modification of Remarks 1 to 3 in (6) Communication at different potential (1.8 V,
			2.5 V, 3 V) (UART mode)
		41	Modification of table in (7) Communication at different potential (2.5 V, 3 V) (CSI mode)
		42	Modification of Caution in (7) Communication at different potential (2.5 V, 3 V) (CSI mode)
		43	Modification of table in (8) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI
			mode) (1/3)
		44	Modification of table and Notes 1 and 2 in (8) Communication at different potential (1.8
			V, 2.5 V, 3 V) (CSI mode) (2/3)
		45	Modification of table, Note 1, and Caution 1 in (8) Communication at different potential
			(1.8 V, 2.5 V, 3 V) (CSI mode) (3/3)
		47	Modification of table in (9) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI
			mode)
		50	Modification of table, Note 1, and Caution 1 in (10) Communication at different potential
			(1.8 V, 2.5 V, 3 V) (simplified I <sup>2</sup> C mode)
		52	Modification of Remark in 2.5.2 Serial interface IICA
		53	Addition of table to 2.6.1 A/D converter characteristics
		53	Modification of description in 2.6.1 (1)
		54	Modification of Notes 3 to 5 in 2.6.1 (1)
		54	Modification of description and Notes 2 to 4 in 2.6.1 (2)
		J <del>4</del>	